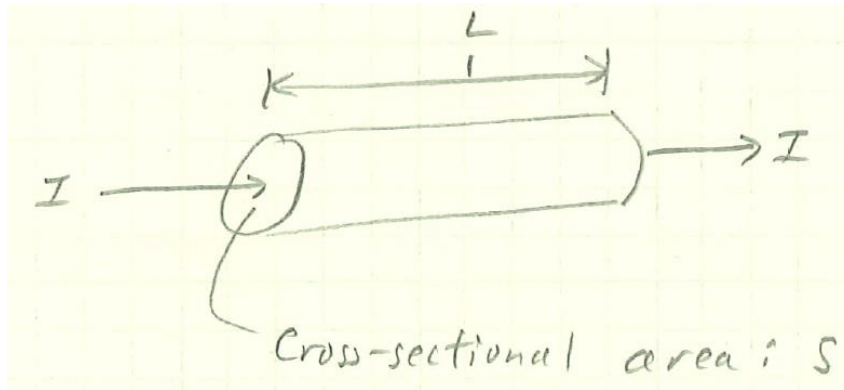


Resistive Sensors

1. Resistance of a section of conductor

Consider this section of a conductor:



$$\text{Resistance: } R = \rho \frac{L}{S}$$

where $\rho \equiv$ resistivity, a material property

$$[\rho] = \Omega\text{-cm}$$

2. Temperature effects

ρ varies with temperature:

$$\text{For metals: } \rho[T] \approx \rho_0(1 + \alpha_T T + \beta_T T^2)$$

where $\rho_0 \equiv$ a resistivity at some reference temperature,
such as 0°C

α_T and $\beta_T \rightarrow$ temperature coefficients

$\alpha_T \equiv$ linear temperature coefficient of resistivity
(TCR)

$$[\alpha_T] = 1/^\circ\text{C} \text{ and } [\beta_T] = 1/(\text{^\circ C})^2$$

For metals: $\alpha_T \sim 10^{-3} \text{ }^\circ\text{C}^{-1}$ and $\beta_T \sim 10^{-7} \text{ }^\circ\text{C}^{-2}$

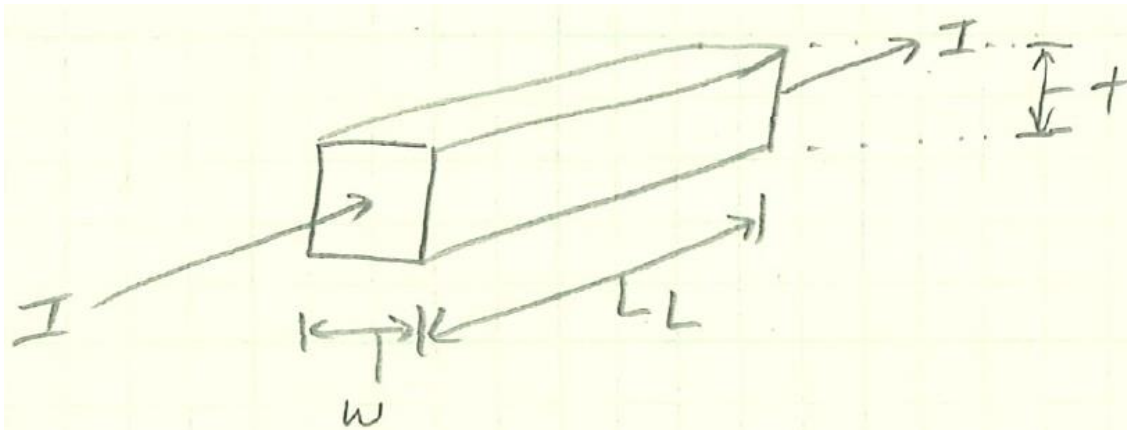
Since $\alpha_T \gg \beta_T$, an approximation is often used: $\rho[T] \approx \rho_o(1 + \alpha_T T)$

Example: at 20°C for Al: $\rho_o = 2.65 \times 10^{-6} \text{ } \Omega\text{-cm}$ and $\alpha_T = 4.3 \times 10^{-3} \text{ }^\circ\text{C}^{-1}$, where T is relative to the reference temperature.

This property can be used to make a metal temperature sensor (more on this later in the course).

3. Strain effects

Consider this section of a conductor:



For most materials, if you axially stretch along L, the cross-sectional area (wt) will shrink.

Let $S = wt \equiv$ cross-sectional area of the conductor

Since $R = \rho \frac{L}{S}$, if $L \uparrow$ and $S \downarrow$, then $R \uparrow$

This leads to Poisson's Ratio: a ratio of the tendency of a material to get thinner in a transverse direction when subjected to axial stretching.

Poisson's Ratio: $\nu = -\frac{\text{transverse strain}}{\text{axial strain}} = -\frac{\varepsilon_{\text{trans}}}{\varepsilon_{\text{axial}}}$

[ν] = dimensionless

Typical values for ν : 0.1 to 0.4

Examining the effects of strain:

$$R = \rho \frac{L}{wt} \quad (1)$$

$$dR = \frac{L}{wt} d\rho + \frac{\rho}{wt} dL - \frac{L\rho}{w^2t} dw - \frac{L\rho}{wt^2} dt \quad (2)$$

$$\therefore \frac{(2)}{(1)} \equiv \frac{dR}{R} = \frac{d\rho}{\rho} + \frac{dL}{L} - \frac{dw}{w} - \frac{dt}{t}$$

$$\frac{dL}{L} \equiv \text{axial strain} = \varepsilon_1$$

$$\frac{dw}{w} \equiv \text{transverse strain} = \varepsilon_w = -\nu\varepsilon_1$$

$$\frac{dt}{t} \equiv \text{transverse strain} = \varepsilon_t = -\nu\varepsilon_1$$

$$\therefore \frac{dR}{R} = \frac{d\rho}{\rho} + \varepsilon_1 + \nu\varepsilon_1 + \nu\varepsilon_1 = \frac{d\rho}{\rho} + \varepsilon_1 + 2\nu\varepsilon_1$$

Note: Young's Modulus: $E = \frac{\text{stress}}{\text{strain}} = \frac{\sigma}{\varepsilon}$

$$[E] = \text{Pa} = \text{N/m}^2 = [\sigma] = [P]$$

Let's define Gauge Factor = GF, where:

$$GF = \frac{dR/R}{\varepsilon_1} = \frac{d\rho/\rho}{\varepsilon_1} + (1 + 2\nu) = \frac{dR/R}{dL/L} = \frac{\Delta R/R}{\Delta L/L}$$

Note: in textbook on p. 86: it should be $\frac{\Delta R/R}{\Delta L/L}$

$\frac{d\rho/\rho}{\varepsilon_1} \rightarrow$ a change in resistivity due to strain \rightarrow Piezoresistive Effect (PE)

$1 + 2\nu \rightarrow$ a change in resistance due to a change in shape \rightarrow Geometric Effect (GE)

$$GF = \frac{\% \text{ change in resistance}}{\% \text{ change in length}} = PE + GE$$

A sensor that makes use of the GE is called a strain gauge.

A sensor that makes use of the PE is called a piezoresistor.

For metals: $GE > PE$

For semiconductors: $PE > GE$

From Table 5.1 in testbook

<u>Material</u>	<u>GF</u>
Metal foils	2-5
Thin film metals	2
Single crystal Si	-125 to +200
Polysilicom	± 30

a. Strain Guages

Example: A certain metal strain guage has a nominal resistance of 1 k Ω , and has a GF = 2. If it experiences a 1% axial strain, what does the resistance become?

Solution

$$\varepsilon_1 = \frac{\Delta L}{L} |_{1\%} = \frac{0.01}{1} = 0.01$$

$$GF = \frac{\Delta R/R}{\varepsilon_1} \rightarrow \Delta R = R\varepsilon_1 GF = (1000)(0.01)(2) = 20 \Omega$$

$$R_{new} = R + \Delta R = 1000 + 20 = 1020 \Omega$$

b. Piezoresistors

Single Crystal Si

P-type: GF up to +200

N-type: GF down to -125

Note: a negative GF means that the resistance decreases with applied strain (tensile strain)

$$\frac{d\rho/\rho}{\varepsilon_1} = PE : \text{what causes the piezoresistive effect?}$$

Answer: The applied strain affects the majority charge carriers in the semiconductor material:

P-Type: strain \uparrow : mobility of the holes \downarrow : $\rho \uparrow$

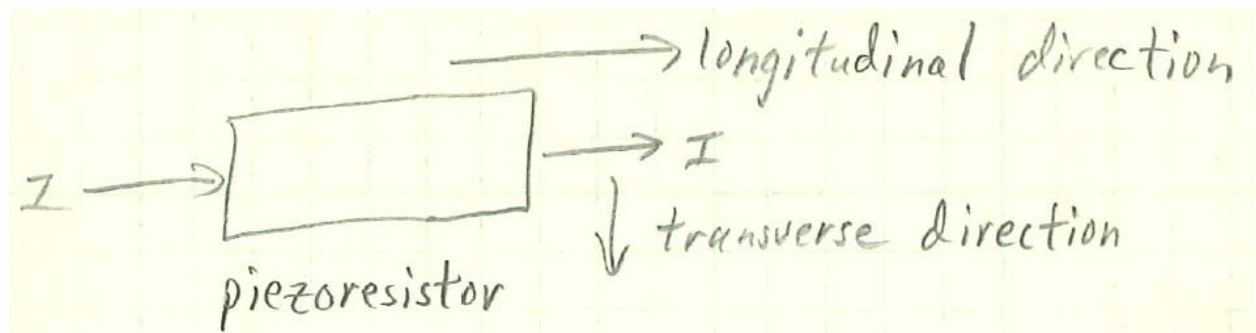
N-Type: strain \uparrow : mobility of the electrons \uparrow : $\rho \downarrow$

Note: this effect is highly dependent on crystallographic orientation, doping level, and temperature → pretty complicated

$$\frac{d\rho}{\rho} = \pi_l \sigma_l + \pi_t \sigma_t$$

Where: π_l = longitudinal piezoresistive coefficient
 π_t = transverse piezoresistive coefficient
 σ_l = longitudinal stress
 σ_t = transverse stress

The longitudinal direction is defined as the direction parallel to the current flow through the piezoresistor.



π_l and π_t are a function of crystal orientation, doping, and temperature.

Polysilicon

Polysilicon is polycrystalline Si, therefore the piezoresistive effect averages over all directions

$$\therefore GF|_{\text{poly Si}} < GF|_{\text{single crystal Si}}$$

Lecture 9/14/22

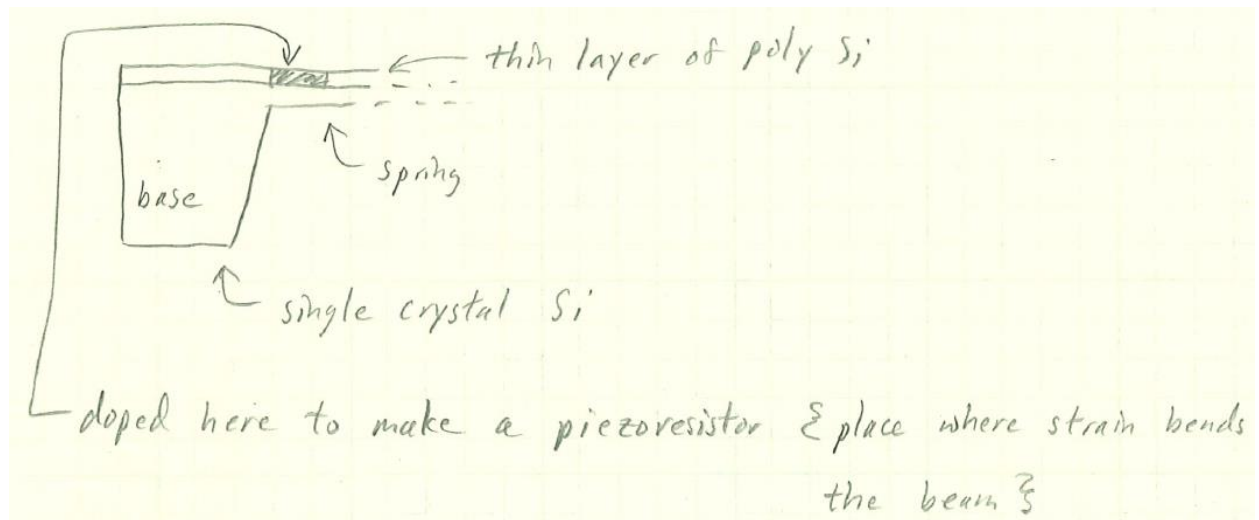
P-type poly Si: GF ~ +30

N-type poly Si: GF ~ -30

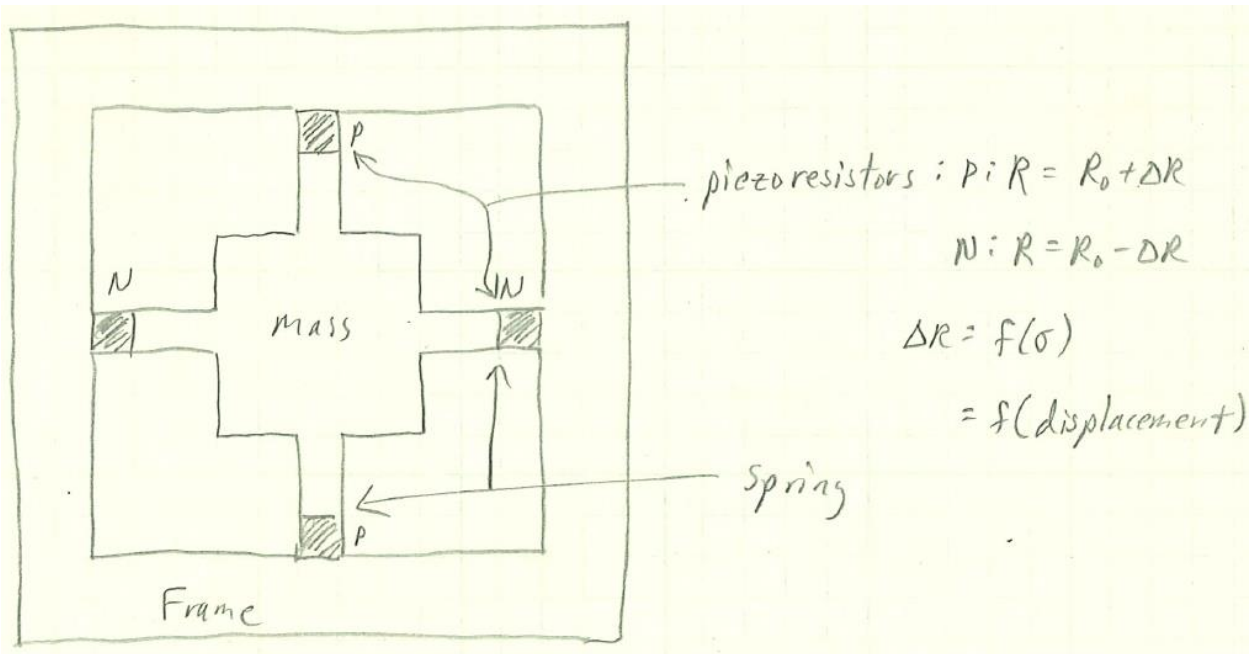
Polysilicon can be deposited as a thin film (up to a few μm), such as by LPCVD, and selectively doped to be N-type or P-type.

Both N-type and P-type polysilicon piezoresistors can be realized on the same chip \rightarrow useful for realizing a Wheatstone bridge type sensor.

The piezoresistor's resistance changes with strain, such as on a spring element:



Consider this device:



With the four piezoresistors above, externally or internally connect them to realize a Wheatstone bridge configuration.

Example Microsensor: HMX2000

Hygrometrix HMX2000 MEMS Humidity Sensor

~2mm

Front Side

Back Side

Glass backing over back side

Polymer coated beams - piezoresistive bridge